

Mag Layers USA, INC

Specification Sheet

P/N: MCM-9070M-SERIES-RU

Products:

Certifications:

Molded Power Chokes

Multilayer Chip Inductors

Lan Transformer

RF Passive / Antennas

<u>Automotive</u>

<u>ISO9001</u>

IATF16949

ISO14001

QC080000

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I. SCOPE:

This specification applies to the Pb Free high current type SMD Common mode filter for MCM-9070M-SERIES

PRODUCT INDENTIFICATION



1 2 3

① Product Code

② Dimensions Code

③ Impedance Code

(1) SHAPES AND DIMENSIONS



A: 9.0±0.5	mm
A1: 9.5±0.5	mm
B: 7.0±0.5	mm
C: 4.8Max.	mm
D: 5.6Typ.	mm
E: 1.5±0.2	mm
F: 2.0±0.2	mm
G: 1.7±0.2	mm

(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

Z : HP 4291B IMPEDANCE ANALYZER (or equivalent)

RDC : CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

I.R : CHROMA MODEL 19073 AC/DC/IR HIPOT TESTER (or equivalent)

(3) CHARACTERISTICS

(3)-1 Operate temperature range $-40^{\circ}C \sim +125^{\circ}C$

(Including self temp. rise)

(3)-2 Storage temperature range -40° C \sim $+125^{\circ}$ C



TABLE 1

MAGLAYERS PT/NO.	Impeda at 10	nce(Ω) 0MHz	Resistance RDC(Ω) Max.	Rated Current	Insulation Resistance	Rated Voltage
	Min.	Тур.	(1 line)	(A) Max.	(MΩ) Min.	(V)Max.
MCM-9070M-301-RU	225	300	6m	6.0	10	80
MCM-9070M-501-RU	450	600	8m	5.5	10	80
MCM-9070M-701-RU	500	700	10m	5.0	10	80
MCM-9070M-102-RU	750	1000	13m	4.0	10	80
MCM-9070M-222-RU	1700	2200	60m	2.5	10	80
MCM-9070M-272-RU	2000	2700	86m	2.0	10	80

CHARACTERISTICS(REFERENCE)





(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS	
Solder ability	The product shall be connected to the test	Apply cream solder to the printed circuit board .	
	circuit board by the fillet (the height is 0.2mm).	Refer to clause 8 for Reflow profile.	
Resistance to	There shall be no damage or problems.	Temperature profile of reflow soldering	
Soldering heat		© 300− soldering	
(reflow soldering)		The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time. The specimen shall be stored at standard atmospheric eric conditions for 1 hour, after which the measurement shall be made.	
Terminal strength	The terminal electrode and the ferrite must	Solder a chip to test substrate , and then laterally apply	
	not damaged.	a load 9.8N in the arrow direction.	
		Printed circuit board	
Strength on PC board	The terminal electrode and the ferrite must	Solder a chip to test substrate and then apply a load.	
bending	not damaged.	Test board:FR4 100×40×1mm R10 rl Fall speed:1mm/sec. 45 45 Dimensions in mm	
High	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit	
temperature	Insulation resistance and DC resistance on the	board,the test shall be done.	
resistance	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.	
	The terminal electrode and the ferrite must not	Temperature : +125±2°C	
	damaged.	Applied voltage : Rated voltage	
		Applied current : Rated current	
		Testing time : 500±12 hours	



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
resistance	Insulation resistance and DC resistance on the	board,the test shall be done.
	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must not	Temperature:+60±2 $^\circ\!\!\mathbb{C}$,Humidity:90 to 95 %RH
	damaged.	Applied voltage : Rated voltage
		Applied current : Rated current
		Testing time : 500±12 hours
Thermal shock	Impedance:Within±20% of the initial value.	1 cycle
	Insulation resistance and DC resistance on the	↓ 30 min.
	specification(refer to clause 2-1) shall be met.	$+125^{\circ}C$ \rightarrow 30 sed
	The terminal electrode and the ferrite must	
	not damaged.	-40°C +\/ \/
		30 min. Testing time:100 cycle
Low	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test
temperature	Insulation resistance and DC resistance on the	circuit board,the test shall be done.
storage	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must	Temperature : -40±2℃
	not damaged.	Testing time : 500±12 hours
Vibration	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
	Insulation resistance and DC resistance on	board,the test shall be done.
	the specification(refer to clause 2-1)	Frequency : 10 to 55 Hz
	shall be met.	Amplitude : 1.52 mm
	The terminal electrode and the ferrite must	Dimension and times : X ,Y and Z directions
	not damaged.	for 2 hours each.
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated
		over the whole of the sample before hard, the sample shall
		then be preheated for about 2 minutes in a temperature
		of $130 \sim 150^{\circ}$ and after it has been immersed to a depth
		0.5mm below for 3±0.2 seconds fully in molten solder
		M705 with a temperature of 245±5°C. More than 75% of the
		electrode sections shall be couered
		with new solder smoothly when the sample is taken out
		of the solder bath.



(5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN) Unit:mm



(6) TEST EQUIPMENT

(6)-1 Impedance

Measured by using HP4291B RF Impedance Analyzer.



(6)-2 DC Resistance

Measured by using Chroma 16502 milliohm meter.



(6)-3 Insulation Resistance

Measured by using Chroma 19073

Measurement voltage : 50v ,Measurement time : 60 sec.





(6) PACKAGING (6)-1 CARRIER TAPE DIMENSIONS (mm)



(6)-2 TAPING DIMENSIONS (mm)









(6)-4 QUANTITY

700pcs/Reel

The products are packaged so that no damage will be sustained.

Please note that the contents may change without any prior notice due to reasons such as upgrading.





TYPICAL ELECTRICAL CHARACTERISTICS



ATTACHMENT-1